

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Kai-Yi Huang</td><td>10/16/2008</td></tr><tr><td>Ta-Hsun Yeh</td><td>10/16/2008</td></tr><tr><td>Yuh-Sheng Jean</td><td>10/16/2008</td></tr></tbody></table>	Name	Execution Date	Kai-Yi Huang	10/16/2008	Ta-Hsun Yeh	10/16/2008	Yuh-Sheng Jean	10/16/2008	
Name	Execution Date								
Kai-Yi Huang	10/16/2008								
Ta-Hsun Yeh	10/16/2008								
Yuh-Sheng Jean	10/16/2008								
RECEIVING PARTY DATA									
Name:	Realtek Semiconductor Corp.								
Street Address:	2 Innovation Rd. II, Science Park								
City:	HsinChu								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12277309</td></tr></tbody></table>	Property Type	Number	Application Number:	12277309					
Property Type	Number								
Application Number:	12277309								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	WINSTON HSU								
Total Attachments: 2 source=530733#page1.tif source=530733#page2.tif									

CH \$40.00 12277309

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PATENT
REEL: 021884 FRAME: 0836

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Kai-Yi Huang Nationality: R.O.C.

Name: Ta-Hsun Yeh Nationality: R.O.C.

Name: Yuh-Sheng Jean Nationality: R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Realtek Semiconductor Corp.

Address: 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

" INTEGRATED INDUCTOR STRUCTURE"

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this OCT 16 2008 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Kai-Yi Huang

Kai Yi Huang

Ta-Hsun Yeh

Ta-Hsun Yeh

Yuh-Sheng Jean

Yuh-Sheng Jean